Product Change Notification

104546 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geography location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 104546 - 00

Change Title: 32Mb Advanced + Boot Block Flash with 8 Mb SRAM, PCN 104546-00, FFF, SRAM changes from .15µm/.18µm lithography to .10µm/.13µm

Date of Publication: November 22, 2004

Type of Change Notification:

FFF - (Form-Fit-Function)

Key Characteristics of the Change:

Process

Forecasted Key Milestones:

Date of Samples Availability:	Dec 22, 2004
Date of Qualification Data Availability:	Feb 11, 2005
Date Customer Must be Ready to Receive Post-Conversion Material:	Feb 23, 2005

Description of Change to the Customer:

Intel will begin assembling 32/8 C3 stacked devices with existing SRAM suppliers which are converting silicon lithography to .10µm and .13 µm from .15 µm and .18µm respectively.

The new SRAMs have the same functional specifications as the existing SRAM source. There is no change to the datasheet of the 32/8 C3 stacked device. The 'Products Affected' table below gives the part numbers for the 32/8 C3 devices. Intel will not be modifying the part number.

Intel will fully qualify both these new SRAMs and the new stack devices will meet Intel's stringent quality and reliability standards.

This will improve supply flexibility to better serve the customers taking this device.

Customer Impact of Change and Recommended Action:

Intel does not anticipate any impact to customer applications. This SRAM lithography change meets Intel's quality and reliability standards and is backwards compatible with Intel's current stacked chip scale package.

Intel will not be modifying the part numbers. The 'Products Affected' table below lists the current part numbers for the 32/8 C3 stacked devices. Product may be shipped interchangeably after the Key Mikestone dates listed above. Customers must be positioned to accept and use the 32/8 C3 product from either source based on the Key Milestone Dates noted above.

Products Affected / Intel Ordering Codes:

Component Product Table

Product Code	Spec/ROM	Affected MM#
RD38F1020C0ZBL0849857		849857
RD38F1020C0ZBL0S B48	S B48	849855
RD38F1020C0ZBL0S B93	S B93	849856
RD38F1020C0ZTL0849854		849854
RD38F1020C0ZTL0S B48	S B48	849852
RD38F1020C0ZTL0S B93	S B93	849853

Sample Product Code

Sample Product Code	Sample Spec/ROM	Sample MM#	Description
RD38F1020C0ZBL0Q BC9	Q BC9	864720	.18µm lithography to .13µm
RD38F1020C0ZBL0Q BD7	Q BD7	864728	.15µm lithography to .10µm
RD38F1020C0ZTL0Q BC7	Q BC7	864716	.18µm lithography to .13µm
RD38F1020C0ZTL0Q BD5	Q BD5	864727	.15µm lithography to .10µm

Reference Documents / Attachments:

Document:	Location #:

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 22, 2004	00	Originally Published PCN